

**PCN Number:** 20200805000.1 **PCN Date:** Aug 6 2020

**Title:** Qualification of PTI as a new assembly site for select Devices

**Customer Contact:** [PCN Manager](#) **Dept:** Quality Services



**Proposed 1<sup>st</sup> Ship Date:** Nov 4 2020 **Estimated Sample Availability:** Date provided at sample request

<b>Change Type:</b>		
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials
		<input type="checkbox"/> Wafer Fab Process

**PCN Details**

**Description of Change:**

Texas Instruments Incorporated is announcing the qualification of PTI as a new Assembly site for devices listed below in the product affected section. There are no construction differences between the current and new assembly sites, but there are device symbolization differences:

	<b>FXC</b>	<b>PTI</b>
Device marking differences	<ul style="list-style-type: none"> <li>✓ 'SSSS' present</li> <li>✓ 'XXXXXXXXXXXX-VVSS' Present</li> <li>✓ CE logo bottom right</li> <li>✓ BC label upper right</li> </ul>	<ul style="list-style-type: none"> <li>✓ 'SSSS' removed</li> <li>✓ 'XXXXXXXXXXXX-VVSS' Removed</li> <li>✓ CE logo mid right</li> <li>✓ BC Label bottom right</li> </ul>
Device Marking example Pic		

**Reason for Change:**

Supply continuity

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Anticipated impact on Material Declaration**

<input checked="" type="checkbox"/> No Impact to the Material Declaration	<input type="checkbox"/> Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>
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**Changes to product identification resulting from this PCN:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
Foxconn	FXC	CHN	Chongqing
<b>PTI</b>	<b>PT2</b>	<b>TWN</b>	<b>HSINCHU CITY</b>

Sample product shipping label (not actual product label)

**TEXAS INSTRUMENTS**  
 MADE IN: Malaysia  
 2DC: 20:  
 MSL 2 /260C/1 YEAR SEAL DT  
 MSL 1 /235C/UNLIM 03/29/04  
 OPT:  
 ITEM: 39  
**LBL: 5A (L)TO:1750**

(1P) SN74LS07NSR  
 (Q) 2000 (D) 0336  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483SI2  
 (P)  
 (2P) REV: (V) 0033317  
 (20L) CSO: SHE (21L) CCO:USA  
 (22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

CC3120MODRNMBOBR	CC3220MODASM2MONR	CC3220MODSF12MOBR	CC3220MODSM2MOBR
CC3220MODASF12MONR			



**TI Information  
Selective Disclosure**

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Package QBS Reference: CC3235MODSF12MOB	Product QBS Reference: CC3220MODASF12MON	Product QBS Reference: CC3220MODSF12MOB
TH	Unbiased Temperature and Humidity, 85C/85%RH	500 Hours	1/45/0	-	2/90/0
THB	Temperature and Humidity Bias, 85C/85%RH	1000 Hours	-	-	2/46/0
CDM	ESD CDM	500 V	1/3/0	-	2/6/0
HBM	ESD HBM	2000 V	1/3/0	-	2/6/0
HTOL	Life Test, 85C	1000 Hours	1/30/0	-	2/26/0
HTSL	High Temp. Storage Bake, 125C	1000 Hours	1/45/0	-	2/90/0
SD	Solderability	Solderability	1/5/0	-	2/10/0
TC	Temperature Cycle, -40/125C	400 Cycles	1/45/0	-	-
TC	Temperature Cycle, -40/105C	1000 Cycles	-	2/78/0	2/46/0

- QBS: Qualification By Similarity
- Qualification/QBS Devices CC3220MODASF12MON and CC3220MODSF12MOB are qualified at Moisture Sensitivity LEVEL3-250C. QBS Device CC3235MODSF12MOB is qualified at Moisture Sensitivity LEVEL3-260C.
- Preconditioning was performed for Unbiased Temperature and Humidity, Temperature Cycle, and High Temp. Storage Bake.
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
- **Green/Pb-free Status:**
- Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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